

A 1.1 mega-pixels vertical avalanche photodiode (VAPD) CMOS image sensor for a long range time-of-flight (TOF) system

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Panasonic Corporation, Japan

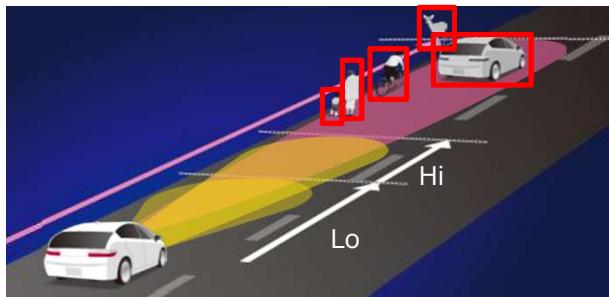
Outline

- 1. Motivation: Targeting a long range/high resolution TOF system**
- 2. Device**
 - Vertical Avalanche Photodiode (VAPD) CMOS image sensor**
 - Capacitive Quenching**
- 3. System**
 - Direct Time-of-Flight by Sub-ranges Synthesis (SRS)**
 - System/Circuit architecture**
 - In-pixel photon counting**
- 4. Demonstration**
 - Long range**
 - Day-time**
 - Improvements in depth-resolution**
- 5. Summary**

Motivation : Lots of opportunities

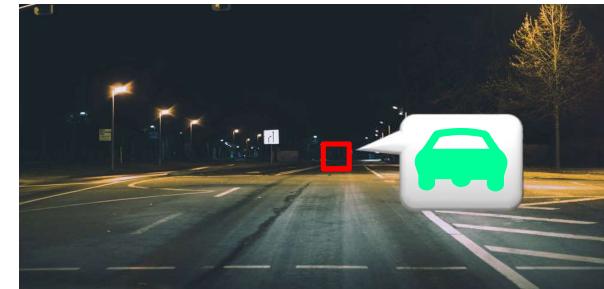
A long range/high resolution direct Time-of-flight (DTOF) systems

AD* sensing



*Autonomous Driving

Road Monitor



Factory Surveillance



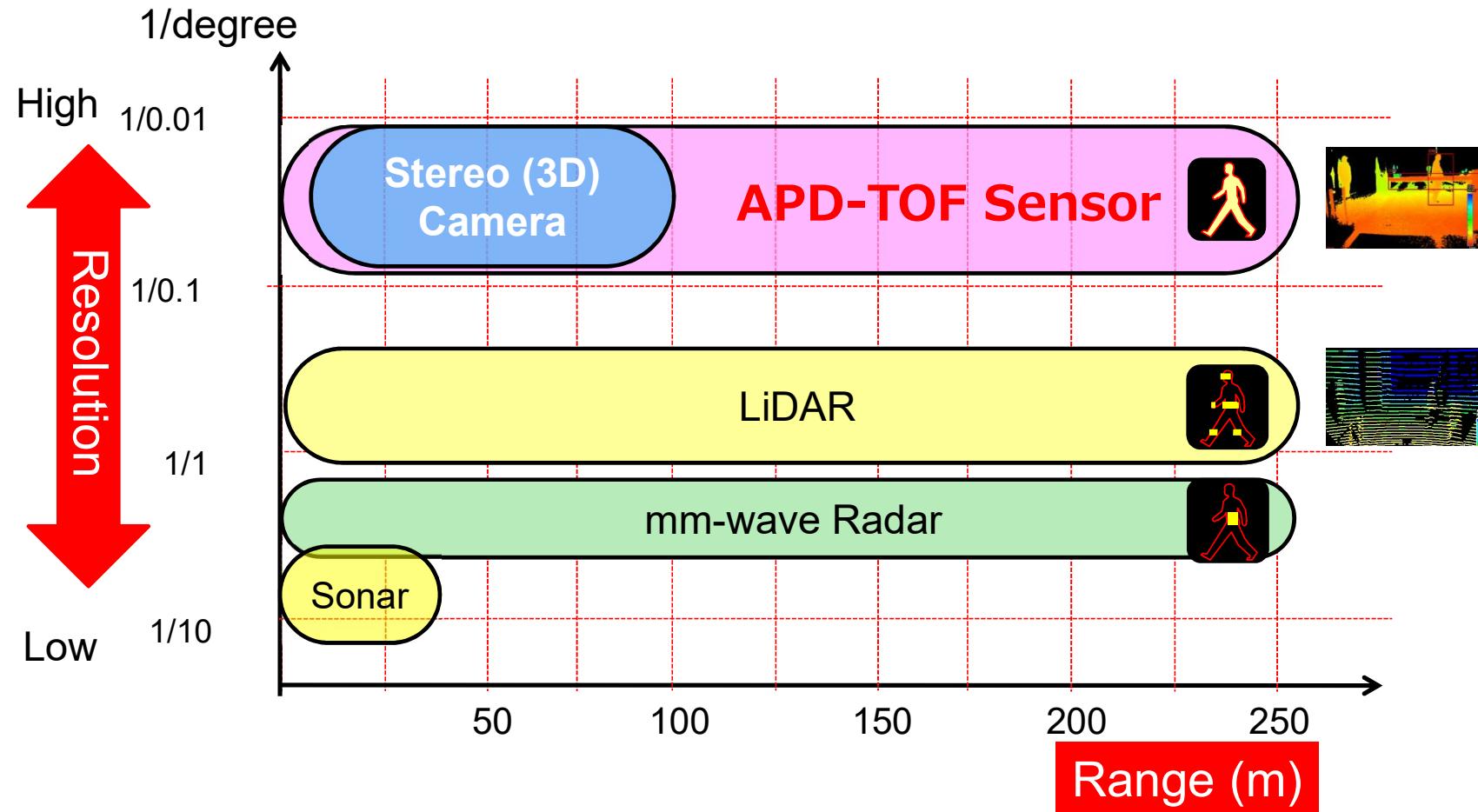
Parking Lot Monitor



Targeted performance and enabling technologies

Range : APD-TOF

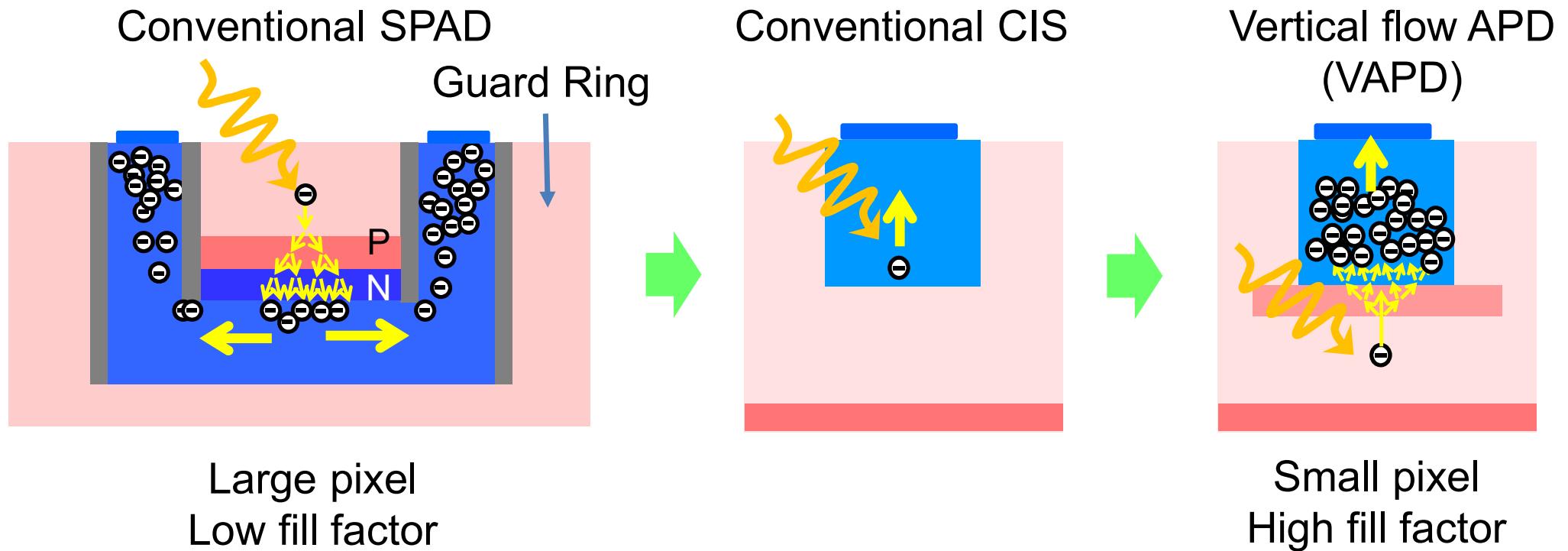
Resolution : CMOS image sensor (CIS)



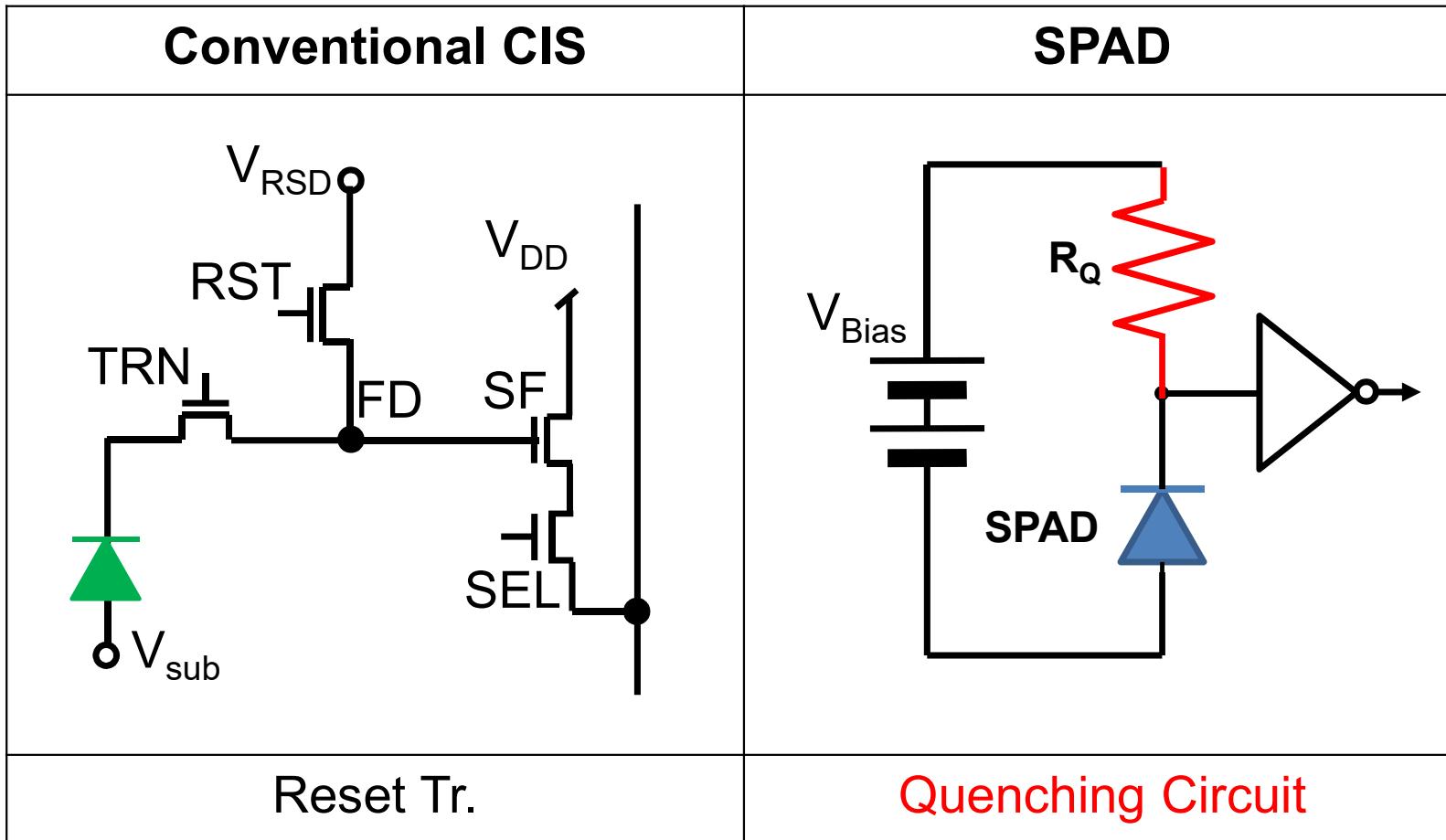
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Vertical avalanche photodiode (VAPD) CMOS image sensor

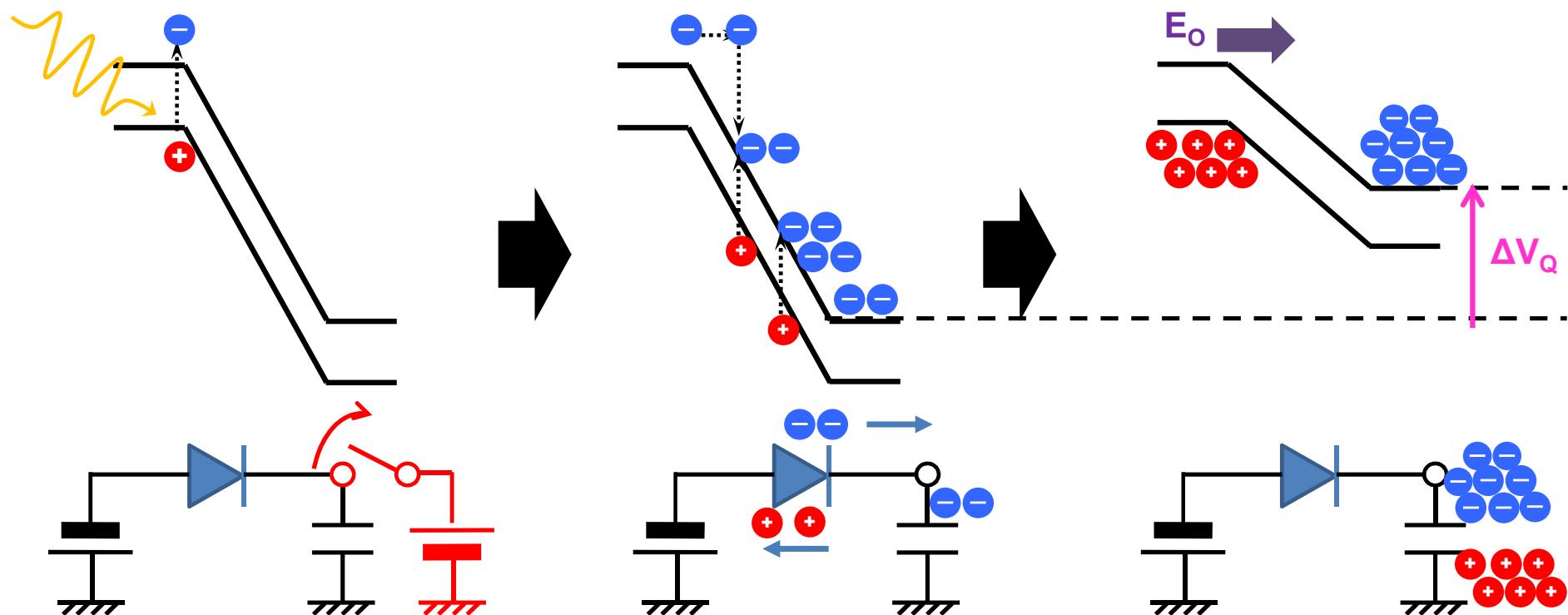


Technical issue : To guarantee quenching



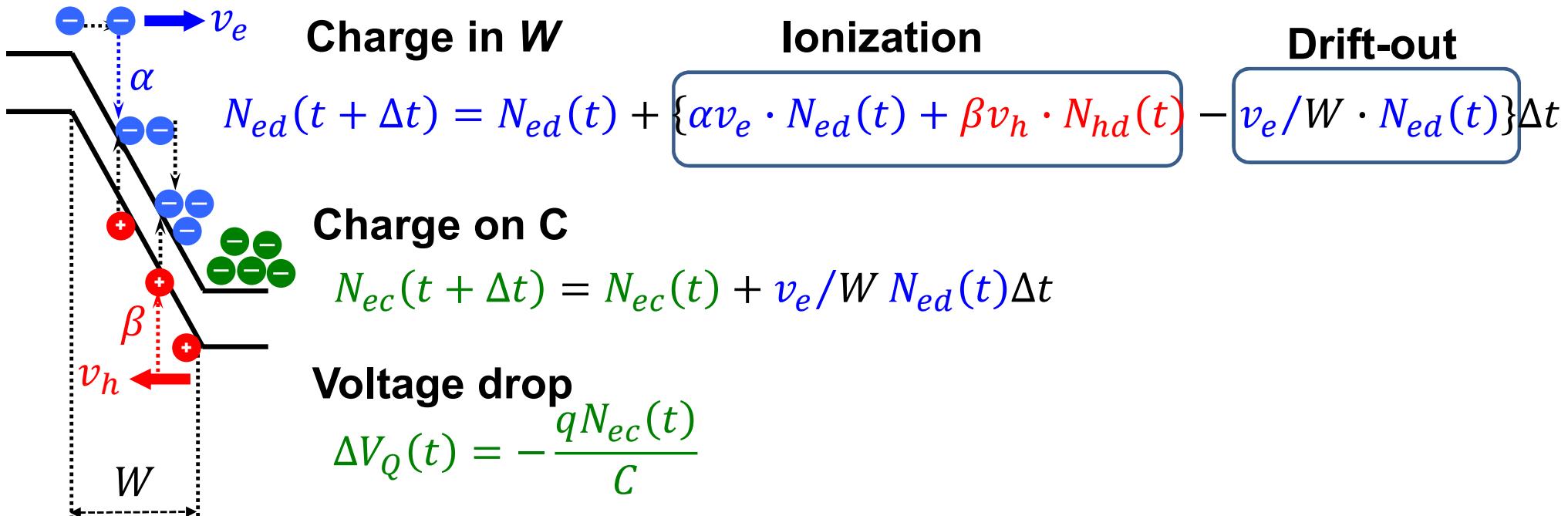
Idea of capacitive quenching

- To set $R_Q \approx \infty$.
- To accommodate all carriers generated. \Rightarrow Need a large capacitor ?



Simulating relaxation quenching process

- ◆ Carriers run with **saturation velocities**.
- ◆ Fixed depletion region width (**W**).
- ◆ Continuity equation → Integration of space dependence. → Time dependence.

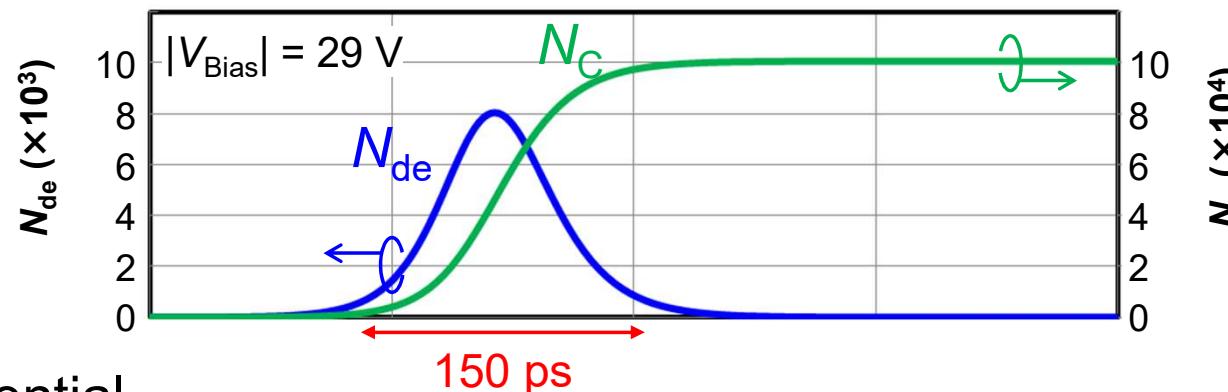


Full set of equations

Meaning	Equations
The number of electrons in a depletion region	$N_{ed}(t)$
The number of electrons in a capacitance	$N_{ec}(t)$
The number of holes in a depletion region	$N_{hd}(t)$
The average time of an electron to pass the depletion region by drift	$t_{1,e} = \frac{W}{2v_{sat,ele}} \text{ (electron)}$ $t_{1,h} = \frac{W}{2v_{sat,hole}} \text{ (hole)}$
Mean time between avalanche multiplications for an electron and for a hole	$t_{0,e} = \frac{1}{v_{sat,ele}\alpha} \text{ (electron)}$ $t_{0,h} = \frac{1}{v_{sat,hole}\beta} \text{ (hole)}$
The Difference equations of electrons and holes in a depletion region	$N_{ed}(t + \Delta t) = N_{ed}(t) + \left\{ \frac{N_{ed}(t)}{t_{0e}} + \frac{N_{hd}(t)}{t_{0h}} - \frac{N_{ed}(t)}{t_{1e}} \right\} \Delta t$ $N_{hd}(t + \Delta t) = N_{hd}(t) + \left\{ \frac{N_{ed}(t)}{t_{0e}} + \frac{N_{hd}(t)}{t_{0h}} - \frac{N_{hd}(t)}{t_{1h}} \right\} \Delta t$
Electrons accumulated in the capacitance	$N_{ec}(t + \Delta t) = N_{ec}(t) + \left\{ \frac{N_{ed}(t)}{t_{1e}} \right\} \Delta t$
Impact ionization ratio of electrons and holes	$\alpha(t) = \alpha_0 \exp\left(-\frac{a}{E(t)}\right)$ $\beta(t) = \beta_0 \exp\left(-\frac{b}{E(t)}\right)$
Electric field in the depletion region	$E = \frac{V}{W}$
Voltage drop due to charge accumulation	$V_Q(t) = V(t = 0) - \frac{qN_{ec}(t)}{C}$

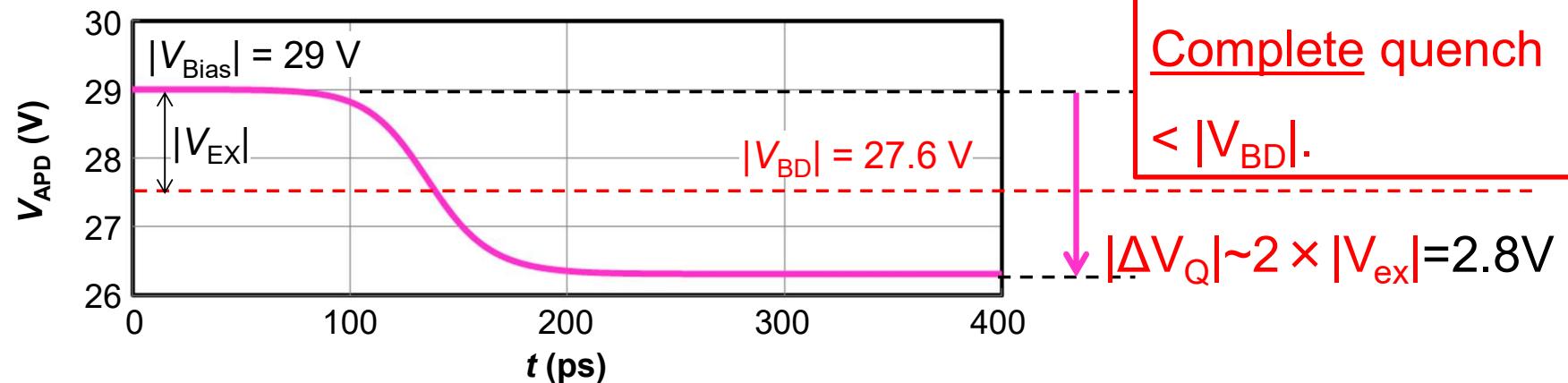
Simulation in time domain

Change of charges



Quenching as fast
as 150 ps.

Change of potential

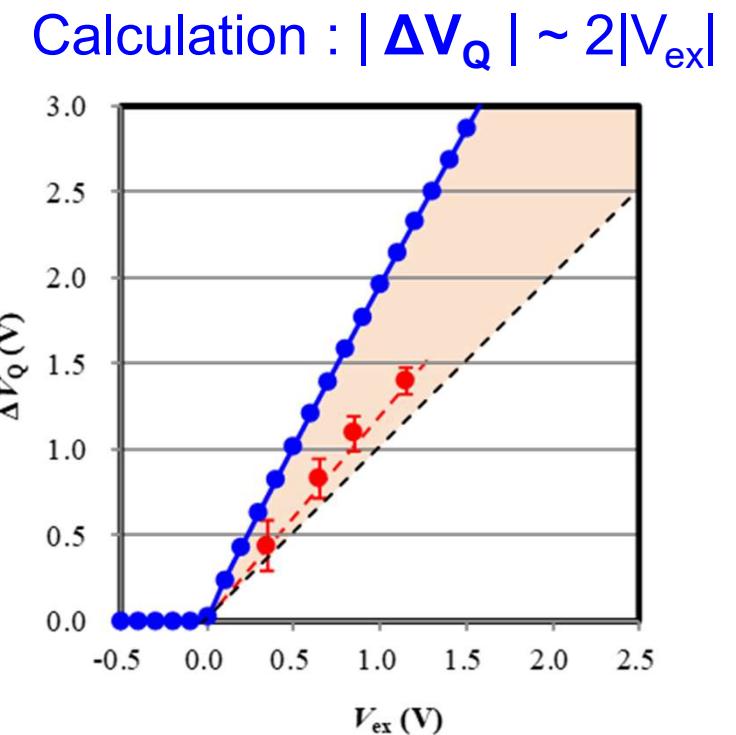
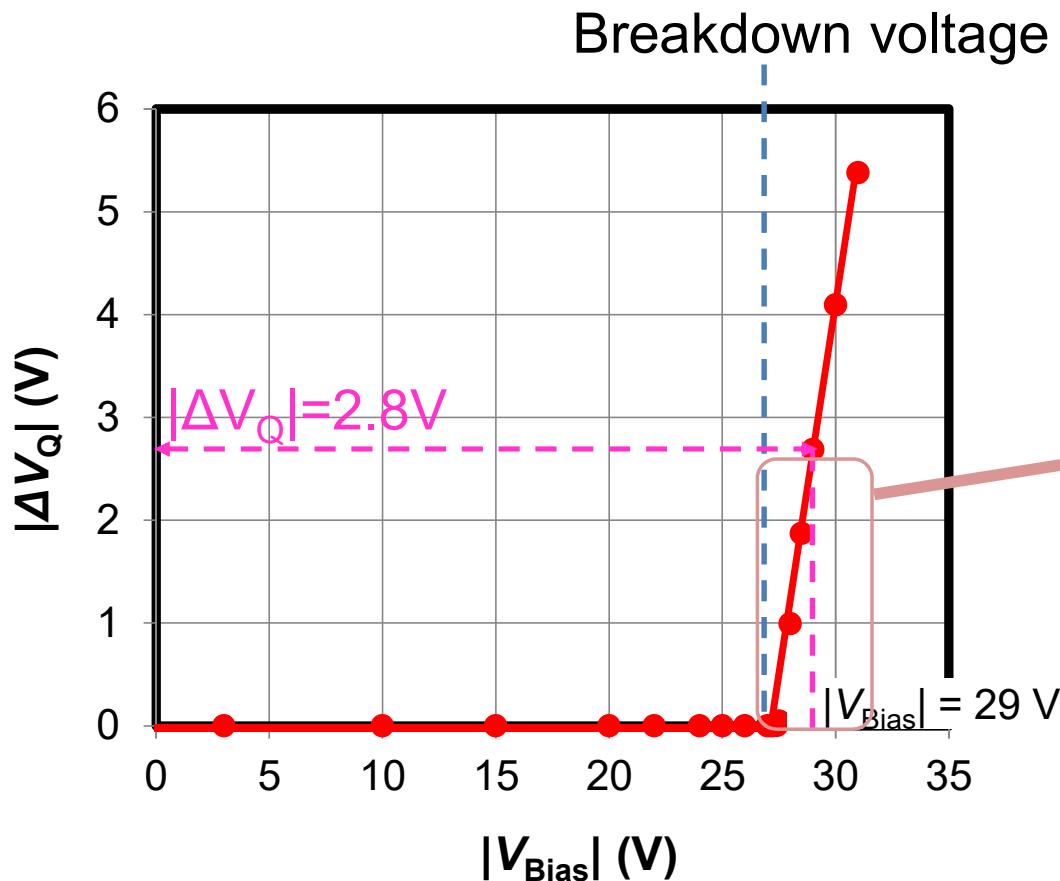


Complete quench
 $< |V_{BD}|$.

$$|\Delta V_Q| \sim 2 \times |V_{ex}| = 2.8 \text{ V}$$

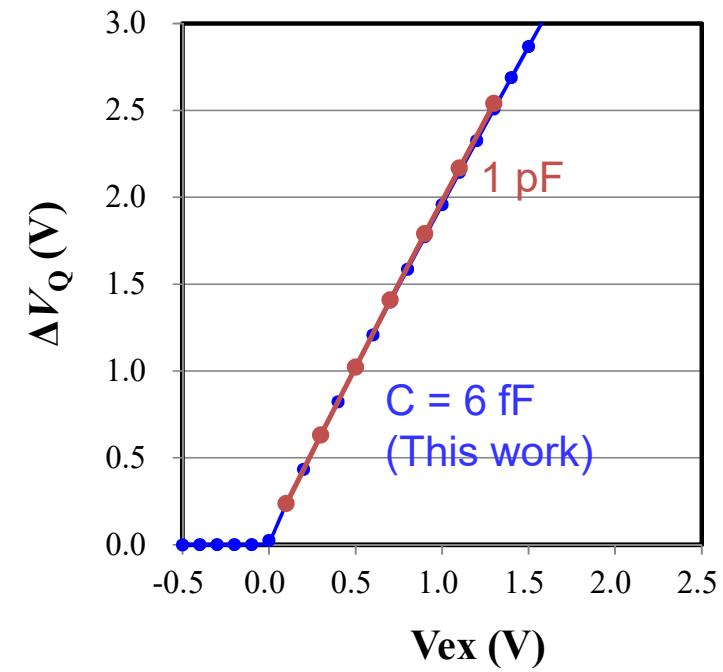
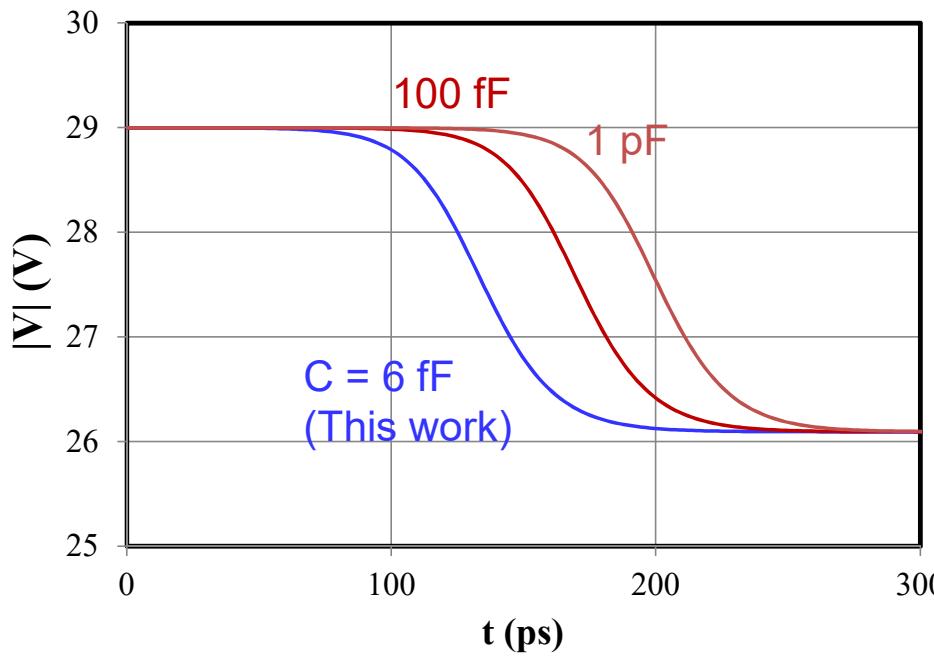
Quenching Voltage (ΔV_Q) depends only on $|V_{\text{Bias}}$

- ΔV_Q proportional to $|V_{\text{Bias}}|$.
⇒ Set the isolation barriers where N_C is stored.



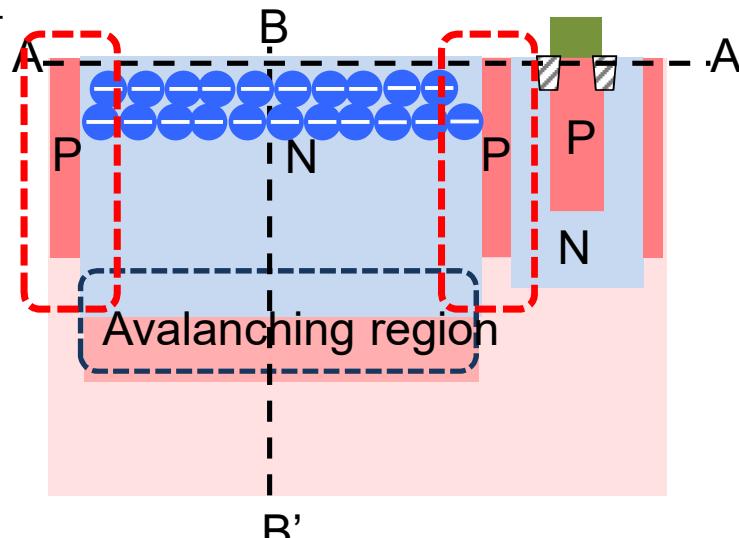
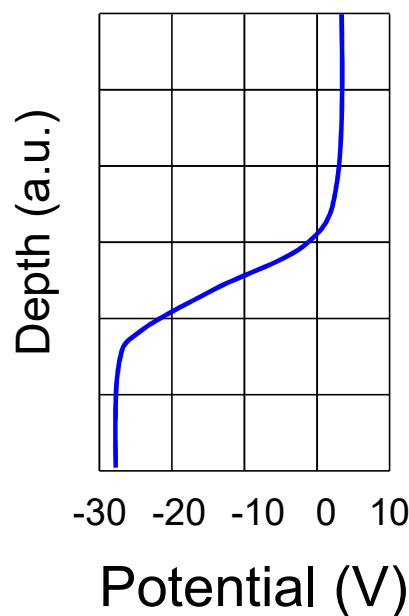
Quenching Voltage (ΔV_Q) depends only on V_{Bias}

- ΔV_Q proportional to $|V_{\text{Bias}}|$.
⇒ Set the isolation barriers where N_C is stored.
- When the capacitance is larger, the quenching time becomes longer.

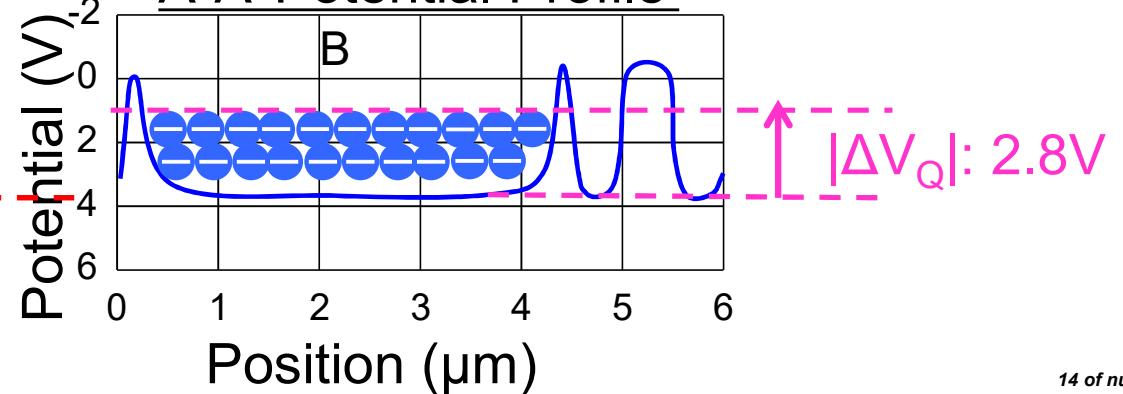


Overflow can be avoided if barrier potential > ΔV_Q

B-B' Potential Profile

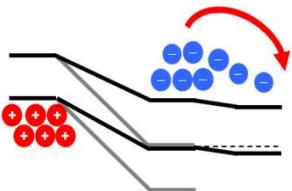
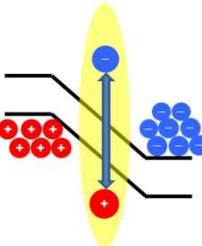
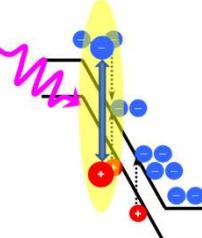


A-A' Potential Profile'

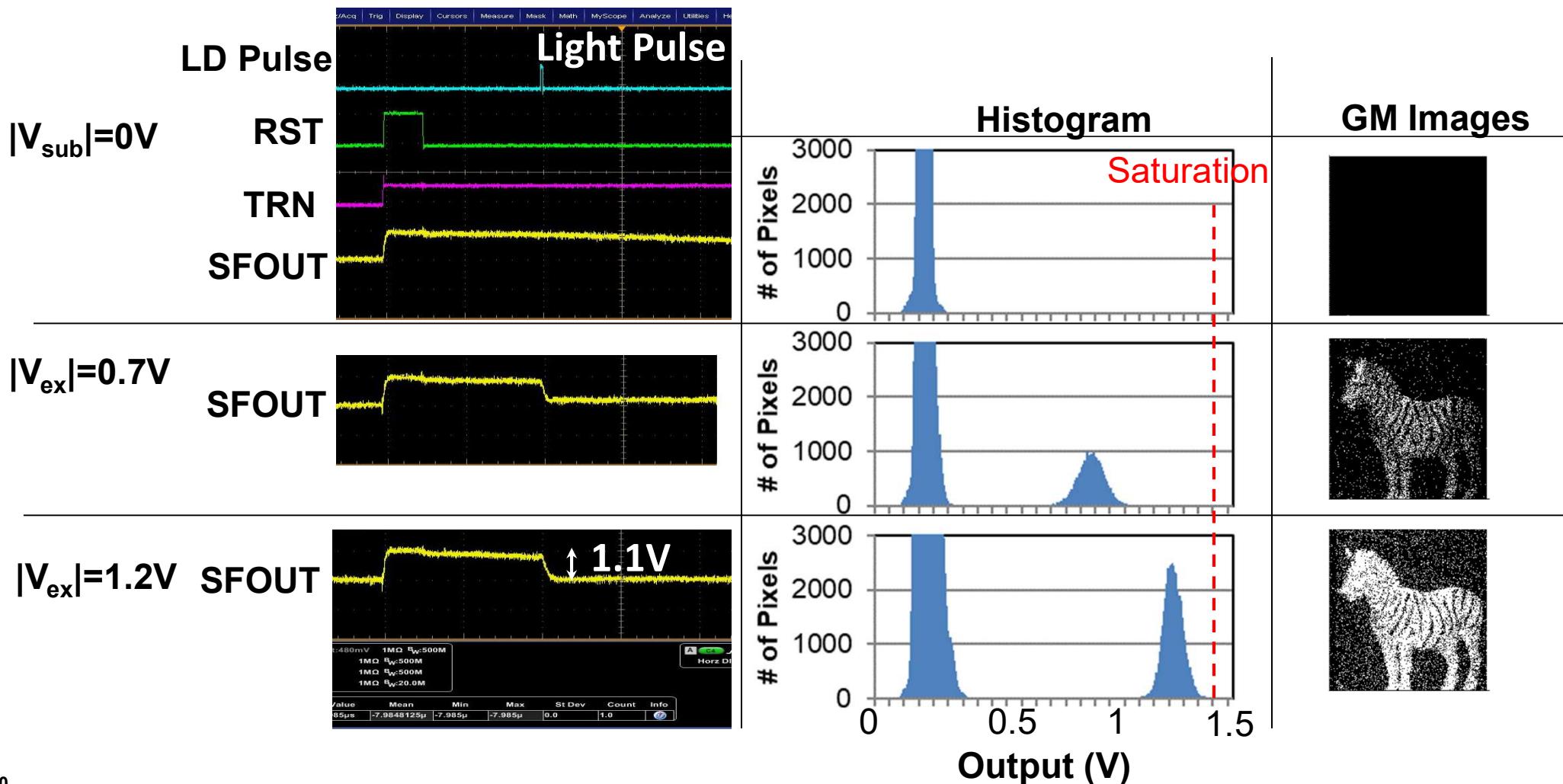


Characteristics of capacitive quenching

Three non-obvious questions are answered.

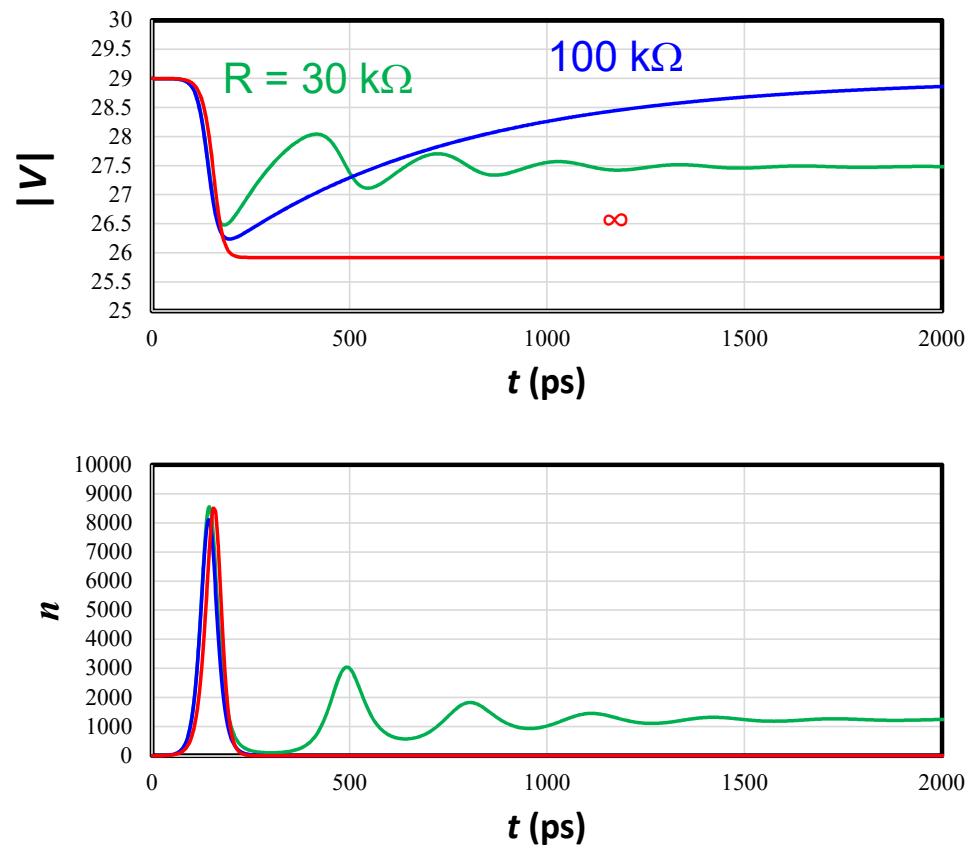
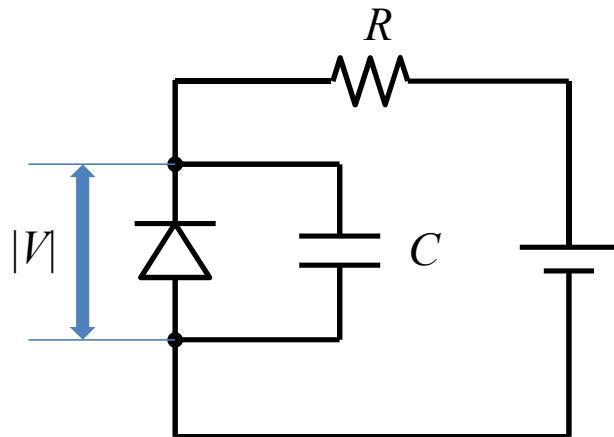
	Phenomenon	Comments
No overflow	 A schematic diagram of a diode structure. Red '+' charges are at the left contact, and blue '-' charges are at the right contact. A red arrow points from the left towards the center, and a blue arrow points from the right towards the center, indicating carrier movement. A curved arrow at the top indicates carrier collection by the electrodes.	<ul style="list-style-type: none">• $V_{\text{Barrier}} > \Delta V_{\text{QL}}$Generated carrier numbers are predictable.
No after-pulse	 A schematic diagram of a diode structure. Red '+' charges are at the left contact, and blue '-' charges are at the right contact. A yellow shaded region covers the central depletion region. A blue arrow points upwards through the yellow region, and a red arrow points downwards from the yellow region towards the right contact, indicating carrier collection and relaxation.	<p>Completely “relaxed”. ⇒ No Geiger mode pulse.</p> <ul style="list-style-type: none">• $\Delta V_{\text{QL}} \sim 2 \times \Delta V_{\text{ex}}$
No double counting	 A schematic diagram of a diode structure. Red '+' charges are at the left contact, and blue '-' charges are at the right contact. A yellow shaded region covers the central depletion region. A purple wavy line represents an electric field or signal pulse. A blue arrow points upwards through the yellow region, and a red arrow points downwards from the yellow region towards the right contact, indicating carrier collection. A dashed line extends from the yellow region towards the right contact, representing a signal path.	<p>Not important during avalanche. Good for synchronous detection ⇒ Direct Time-of-Flight</p>

Verification of capacitive quenching



Simulation of resistive quenching

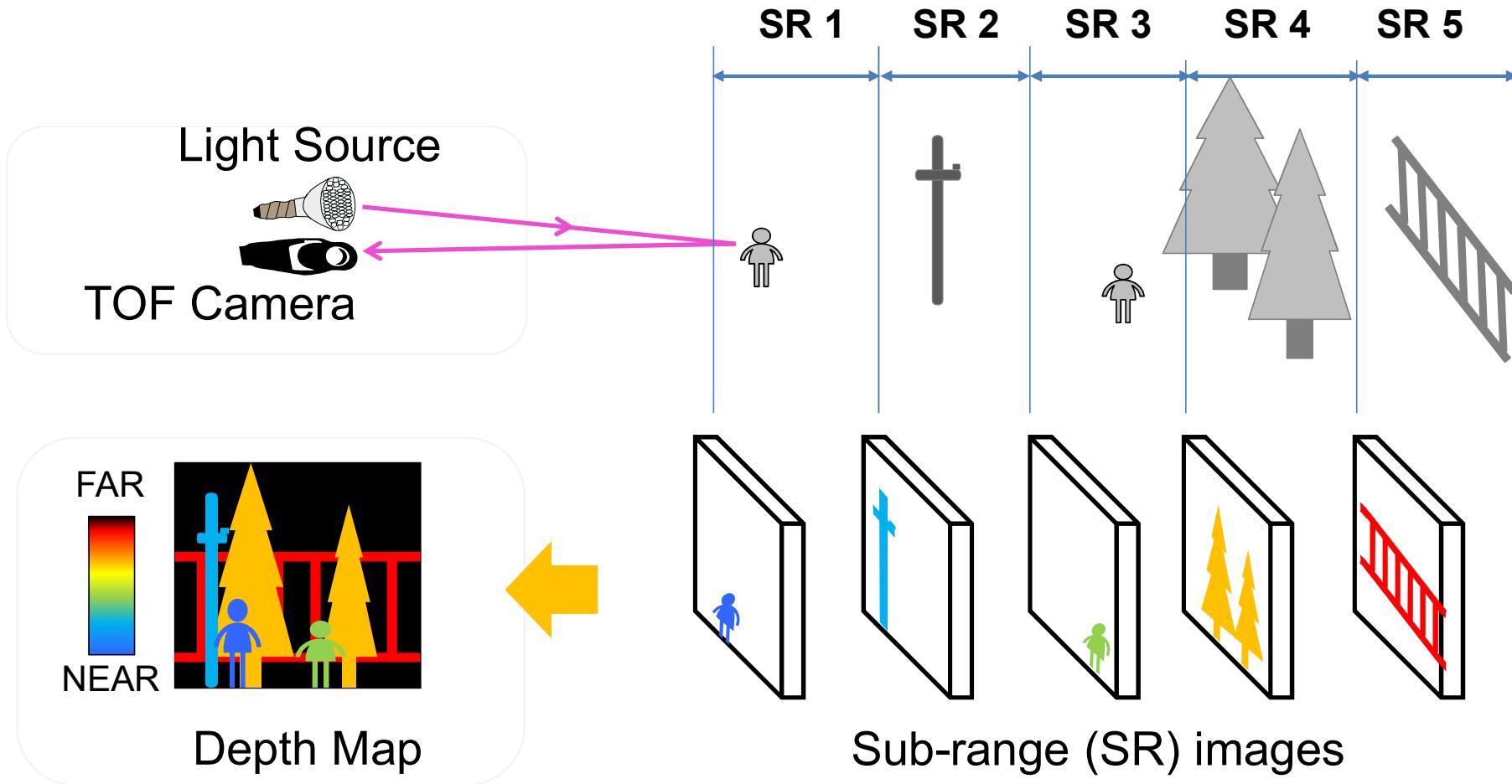
- Reasonable results (need at least few tens of $k\Omega$) are obtained.



Outline

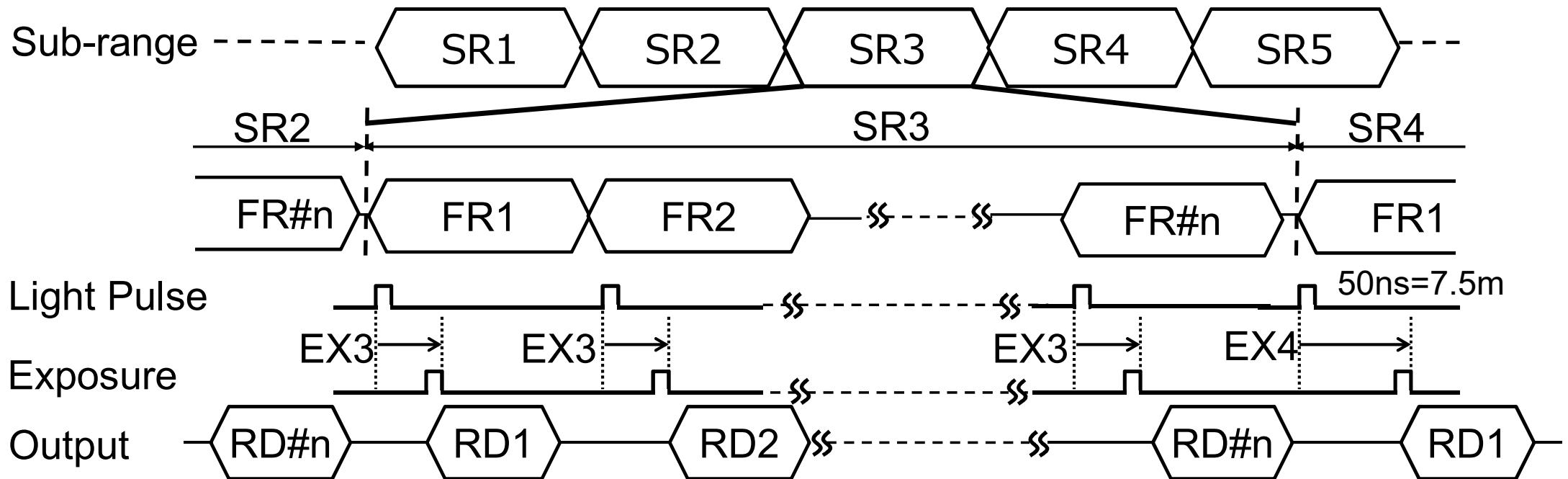
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Principle of Sub-range synthesis method

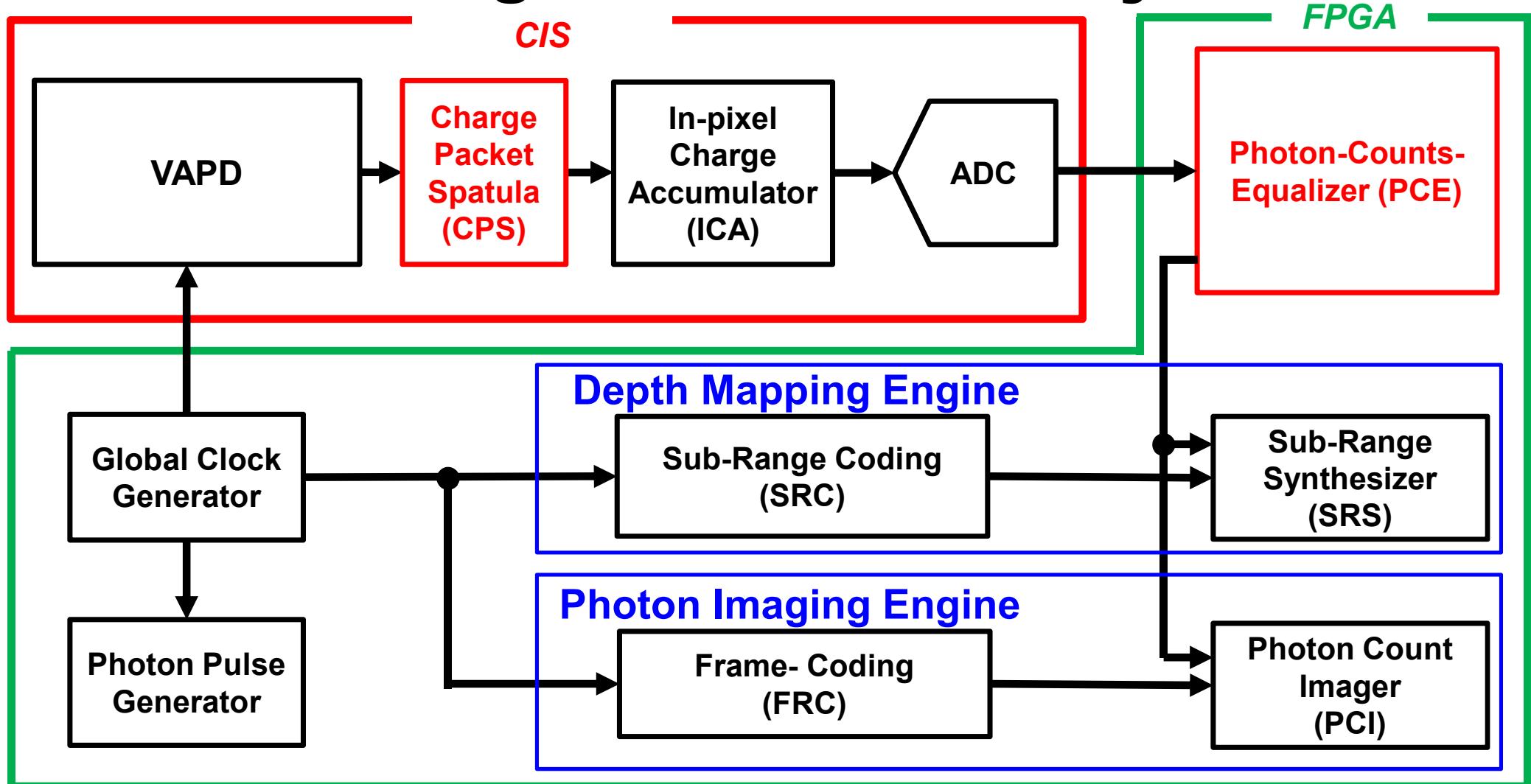


Sub-range image acquisition (typical)

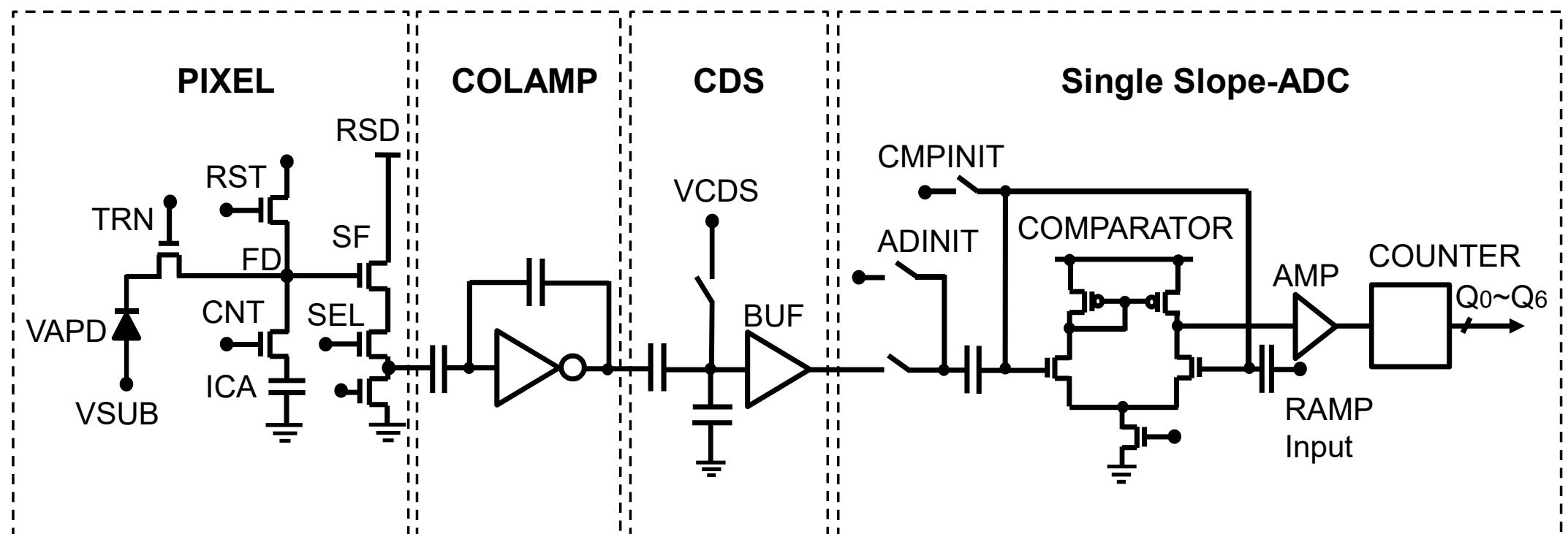
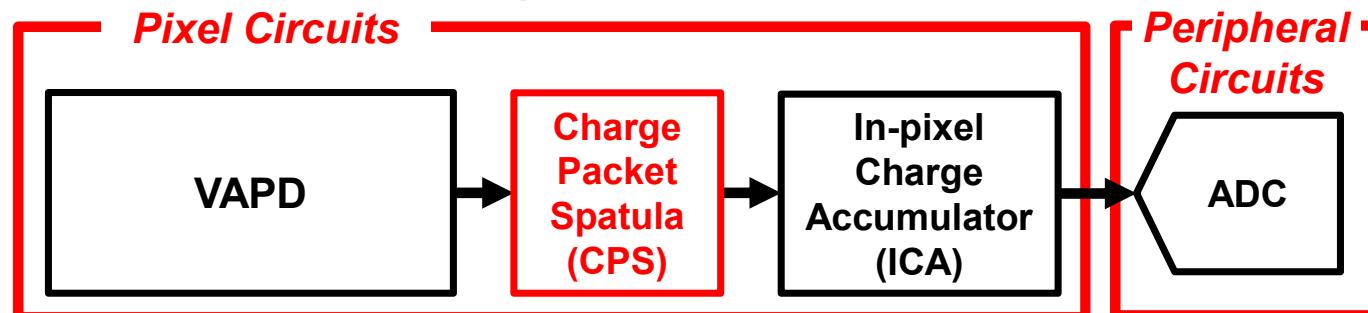
- Laser pulse : 50 kHz
- 2D Speed : 450 fps
- 3D SRS : 30 fps (15 SR images)



Block diagram of APD-ToF system

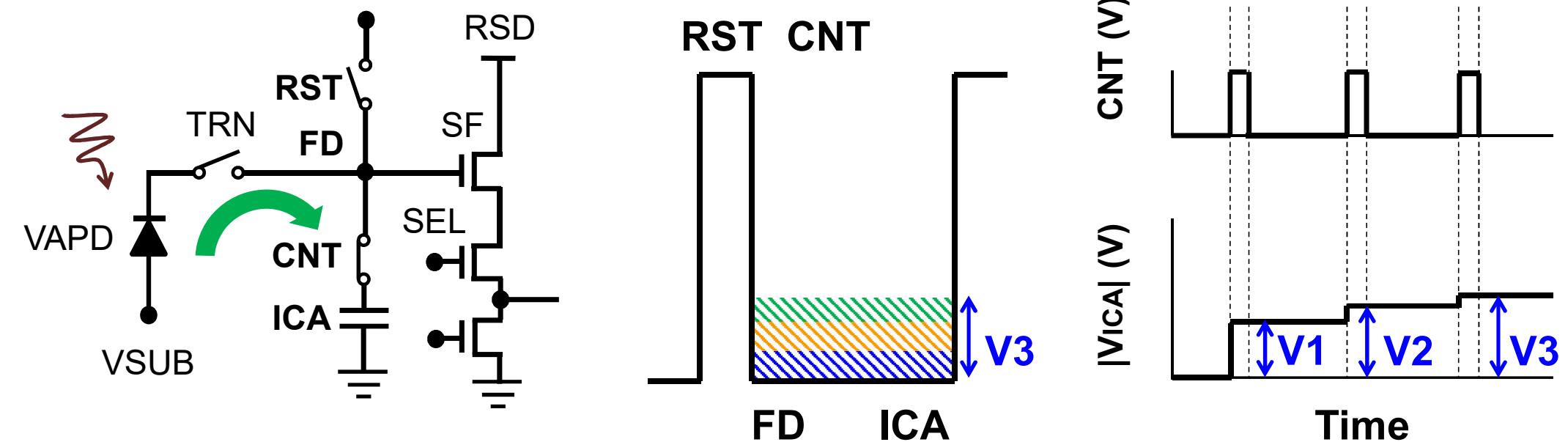


Circuit diagram of VAPD-CIS



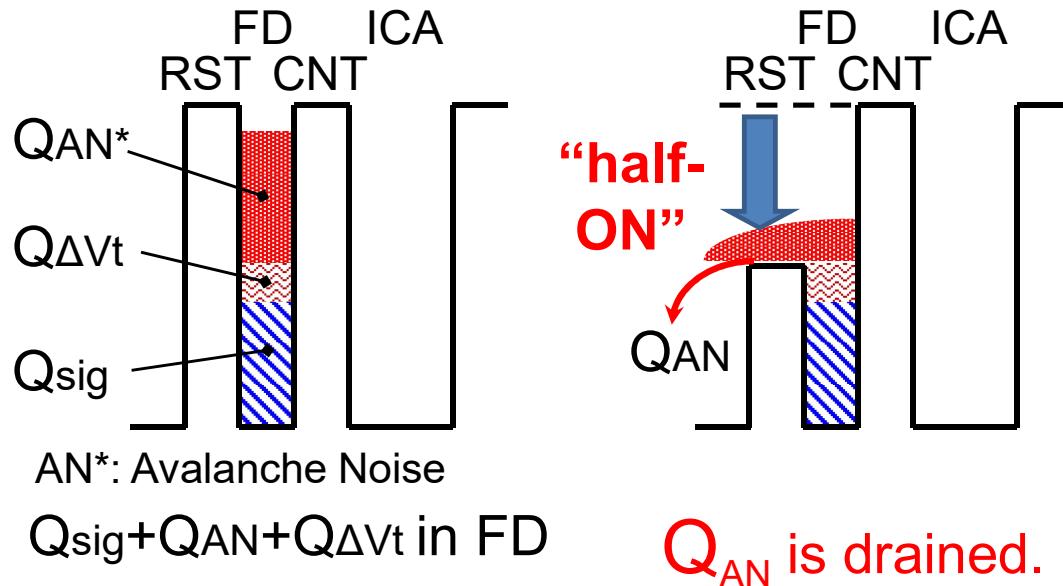
In-pixel charge accumulation (ICA)

- ◆ Non-linearity due to charge sharing operation.
(Shown after 3rd counting.)

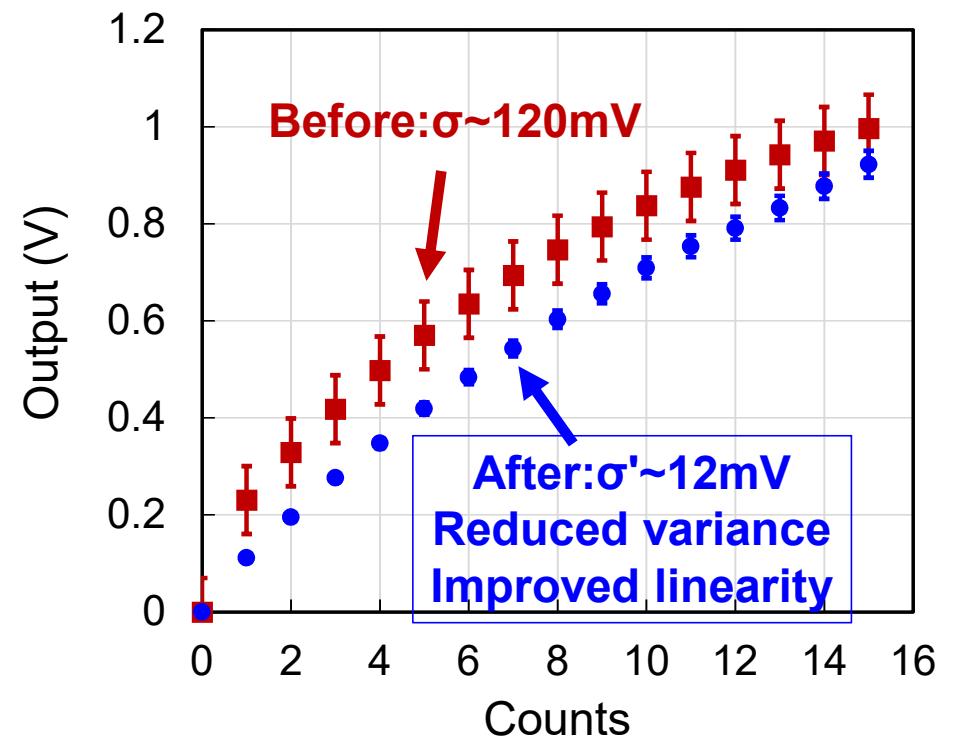


Charge packet spatula (CPS) by RST

Principle of Operation



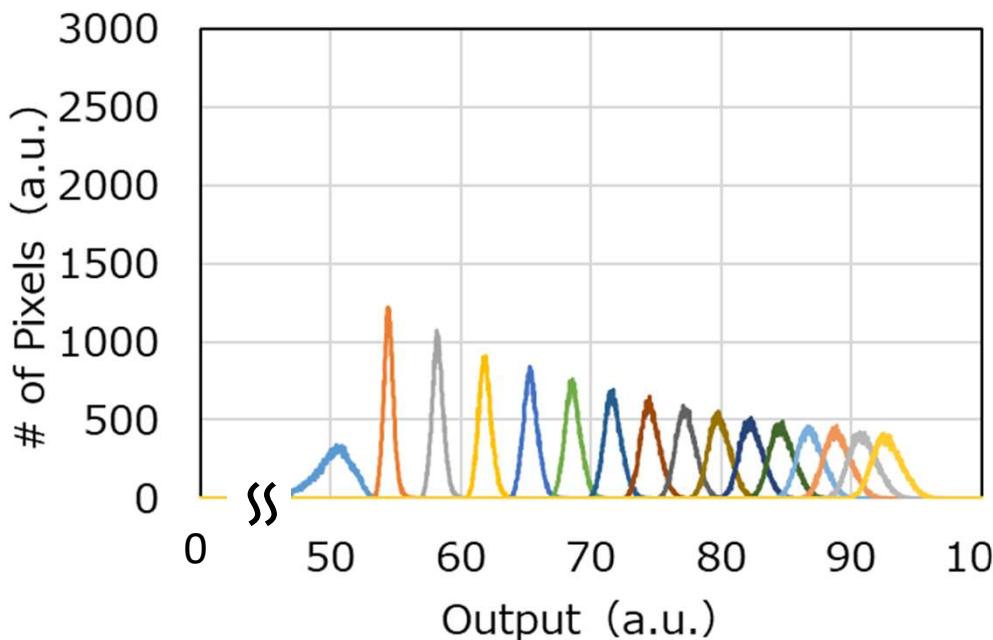
Effectiveness (Before and after CPS)



Off-chip Photon counts equalizer (PCE)

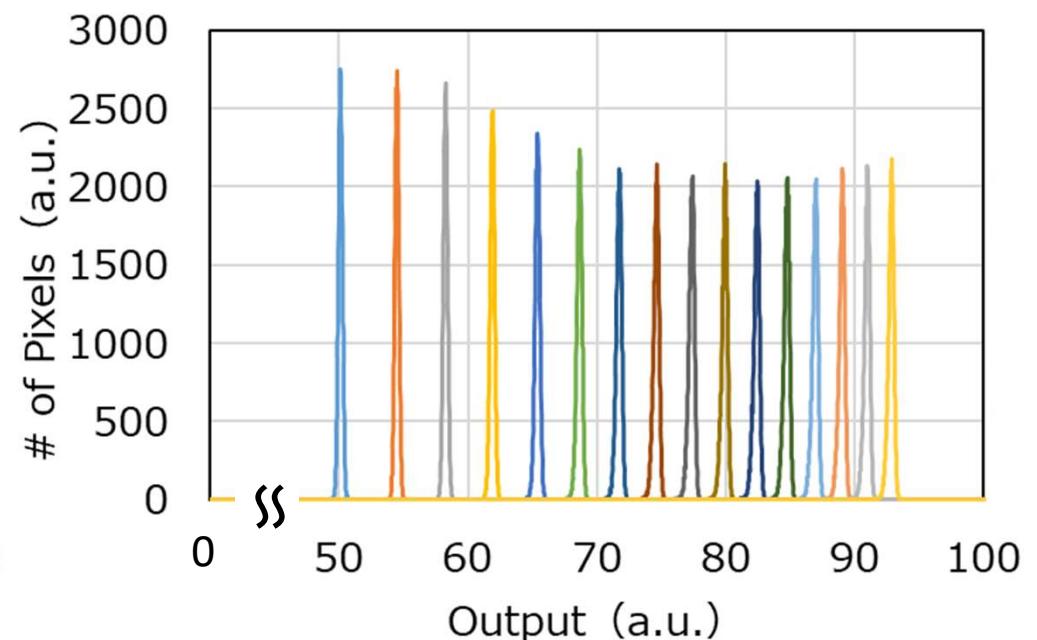
- ◆ Fixed pattern noise due to V_t variation is removed.

Before: Contains FPN (ΔV_t)



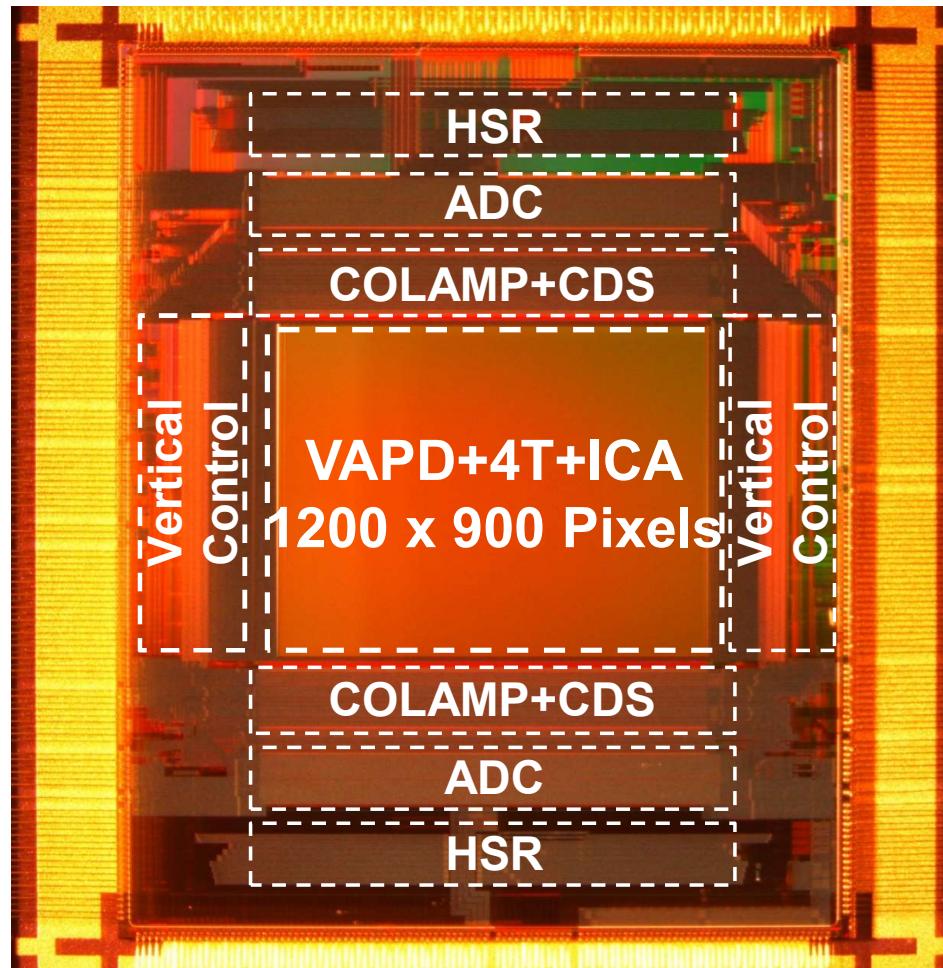
- Broad
- Inhomogeneous

After: Removed FPN (ΔV_t)



- Narrow
- Homogeneous

Chip photograph of VAPD CMOS image sensor



Chip specification (Direct/Indirect-mixed-CIS)

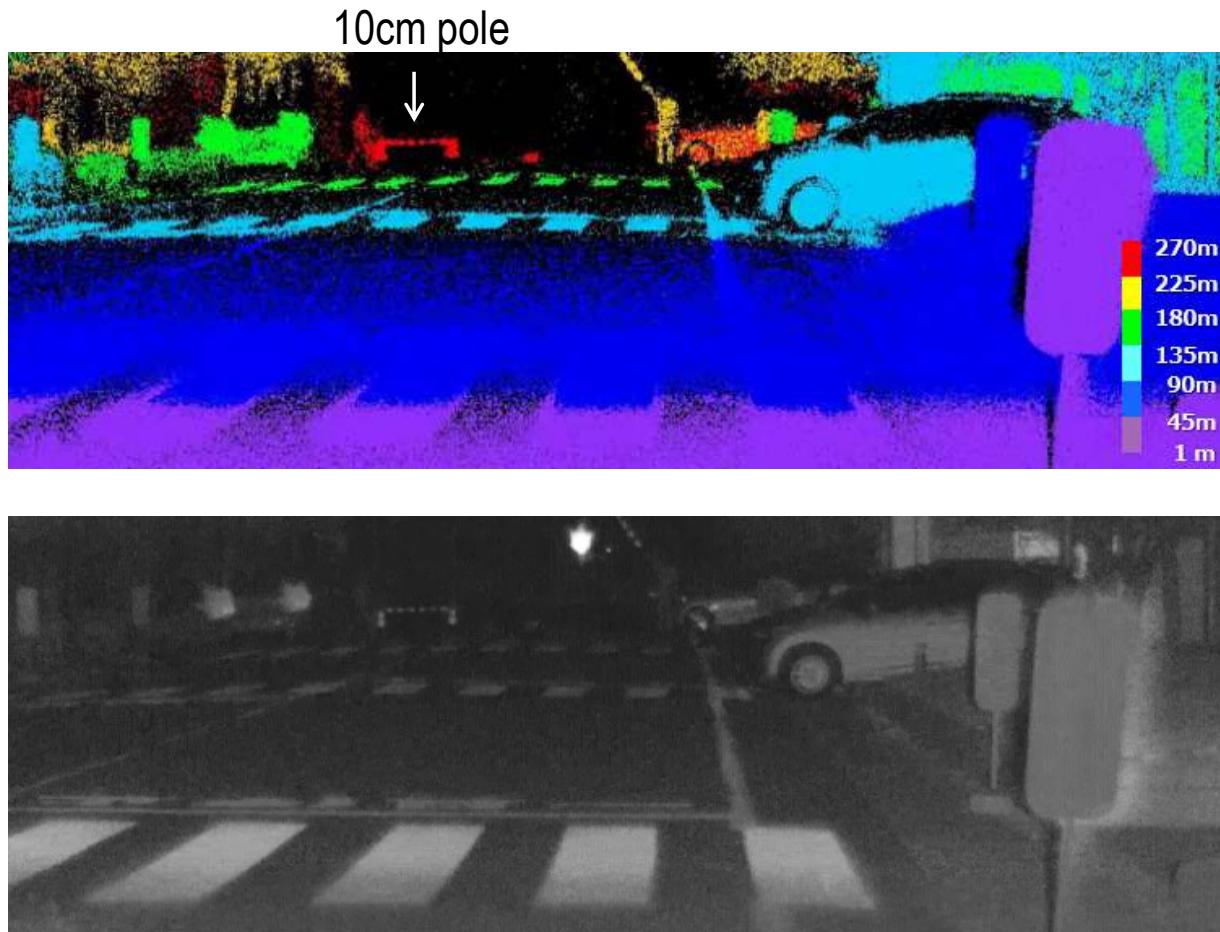
	Direct+Indirect mixed TOF CIS
CMOS Technology	65nm
Pixel Size	6µm
2D Resolution	1200x900
Pixel Type	VAPD (=SPAD)
APD Mode	Geiger
TOF Type	Direct + Indirect
Ranging Scheme	Direct: Photon Counting Indirect: Phase Difference
Maximum Range	250m
Depth Resolution@ Max. Range	1.5m
Depth Resolution@ Min. Range	10cm
2D Frame Rate	450fps

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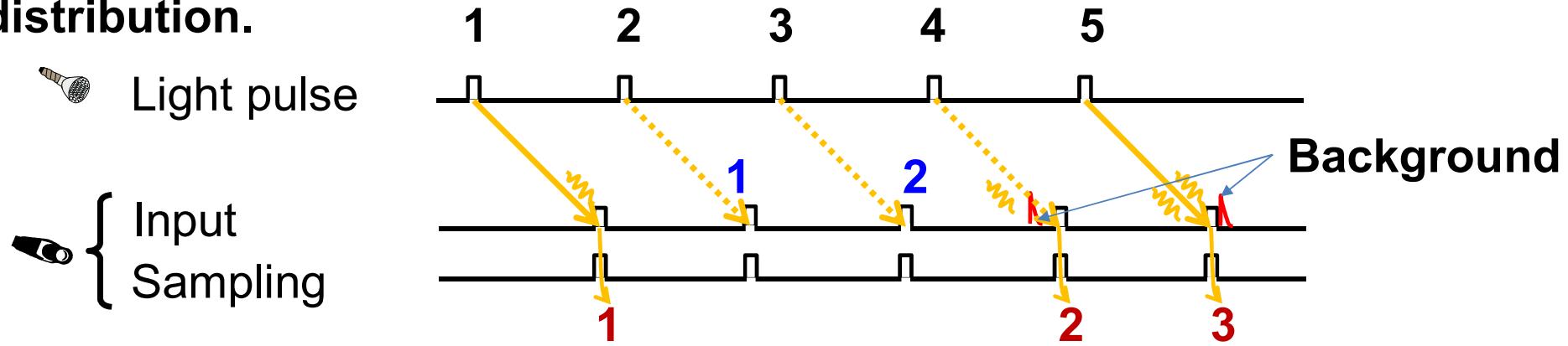
Long range performance (Dark scene)

- ◆ 10cm lateral resolution@250m.



Signal detection process=Binomial distribution

- ◆ Arrival/detection of each photon is a probabilistic process with a binomial distribution.



Signal+Background detection probability

5 samplings

3 successful Signal+BG

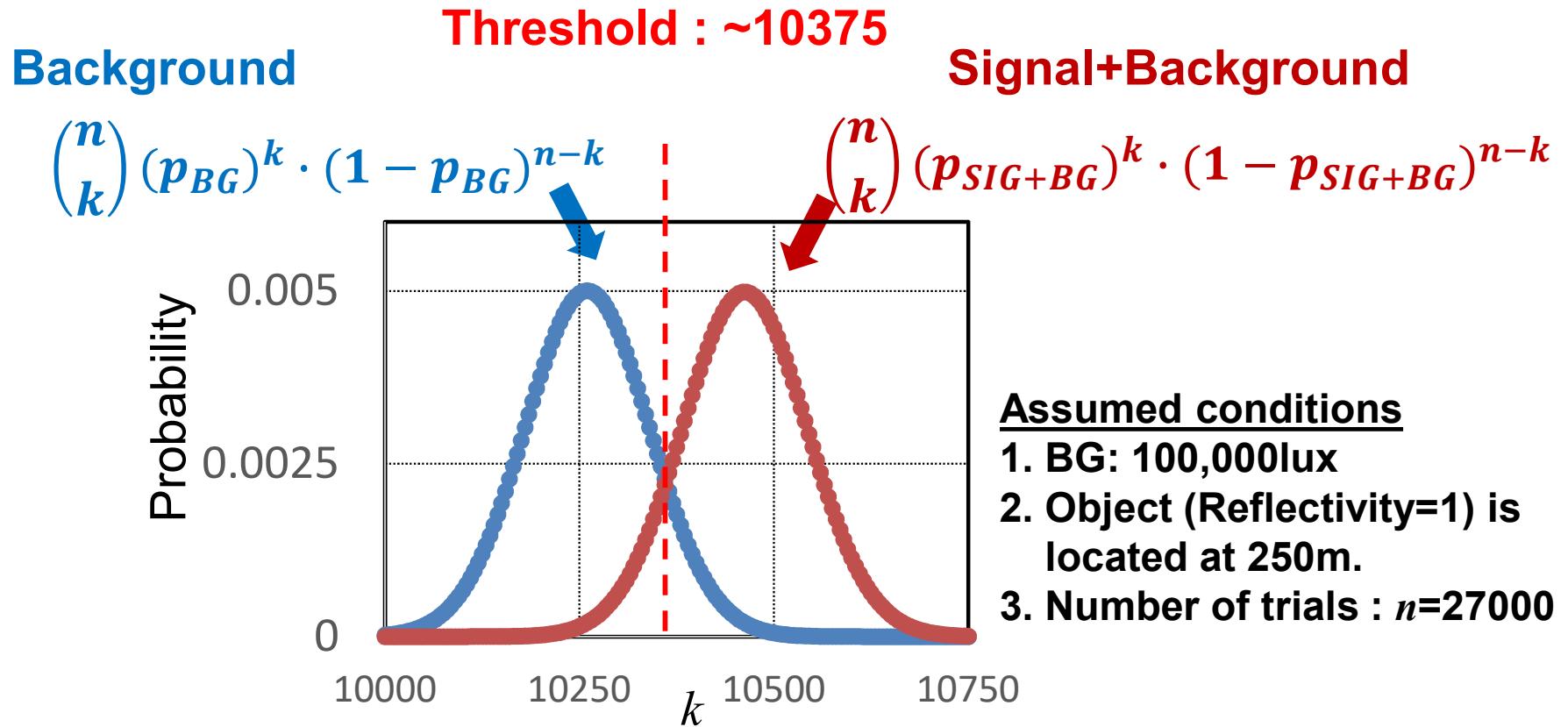
1 missed Signal

$$\rightarrow \binom{5}{3} (p_{SIG+BG})^3 \cdot (1 - p_{SIG+BG})^2$$

General $\rightarrow \binom{n}{k} (p_{SIG+BG})^k \cdot (1 - p_{SIG+BG})^{n-k}$

To distinguish signal from background

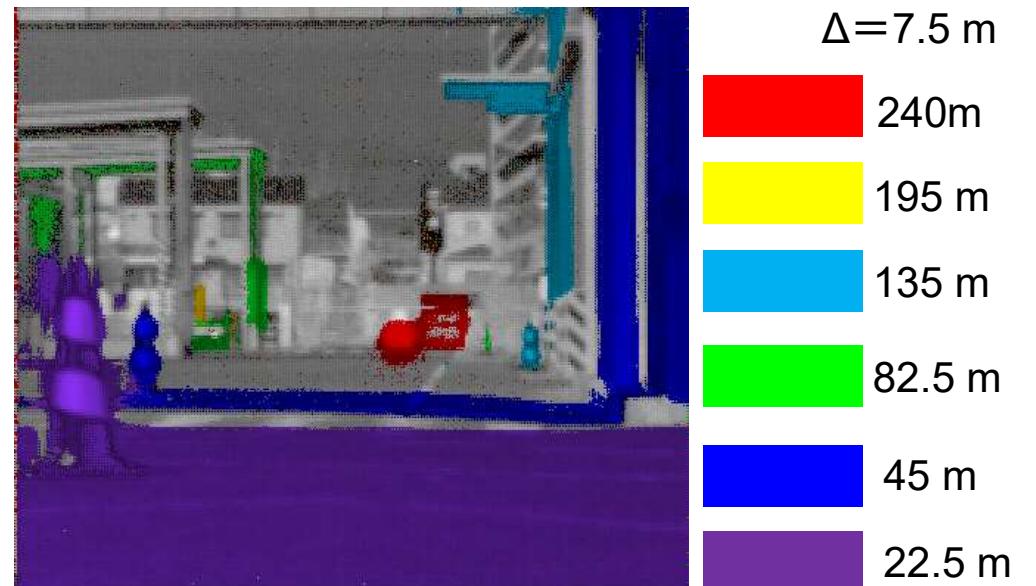
- ◆ More counting for SIG+BG than for BG.



Long (~240 m) ranging under daylight (93000lux)

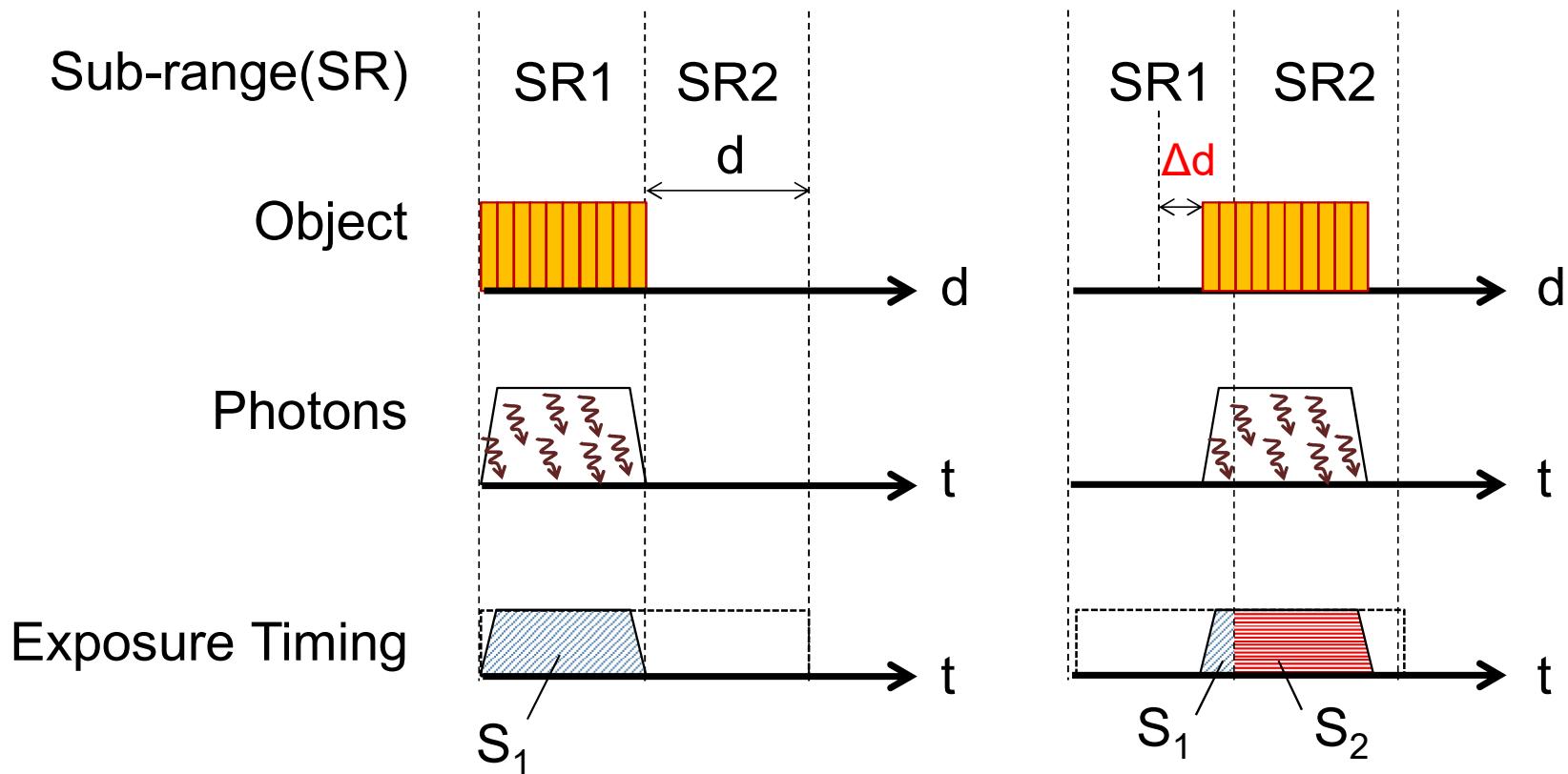


Gradiation Image



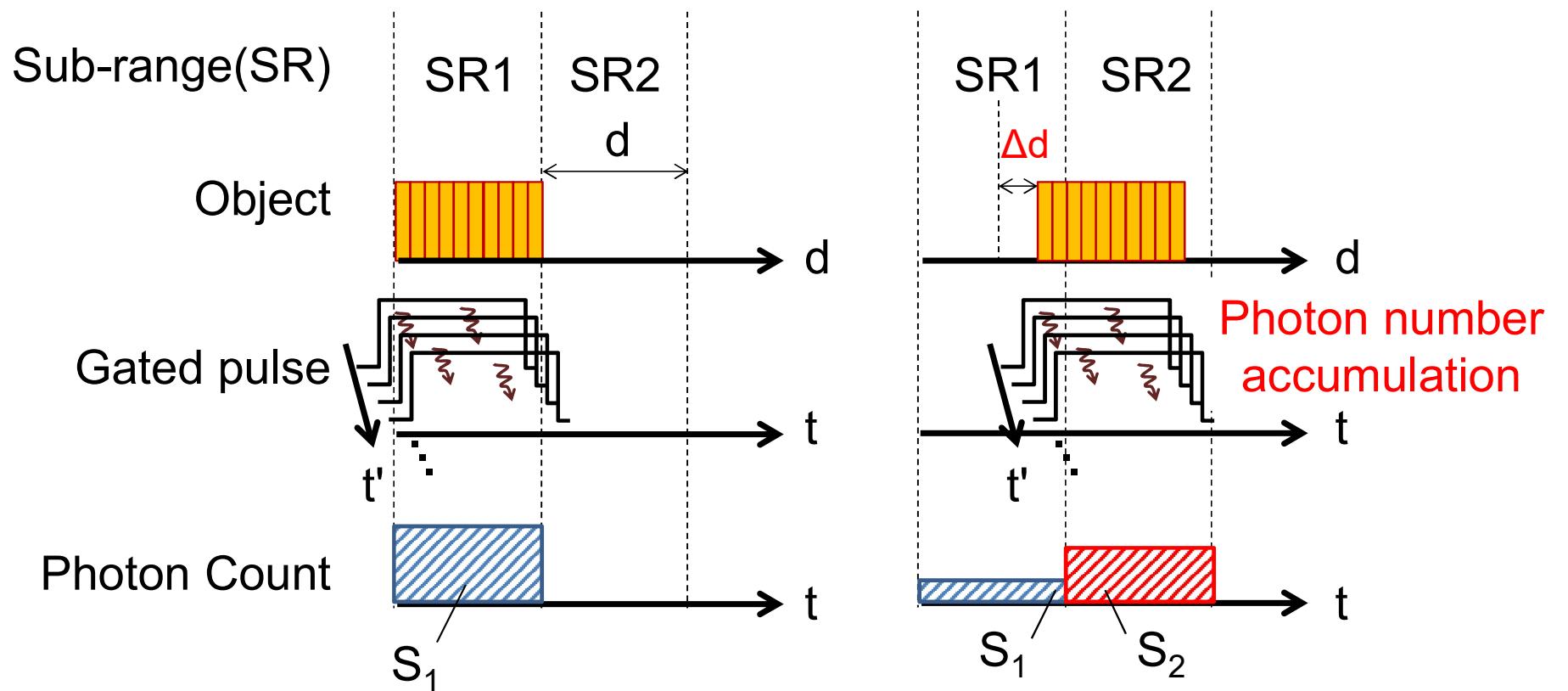
**Gradiation+TOF
Synthesized Image**

Phase differentiation operation



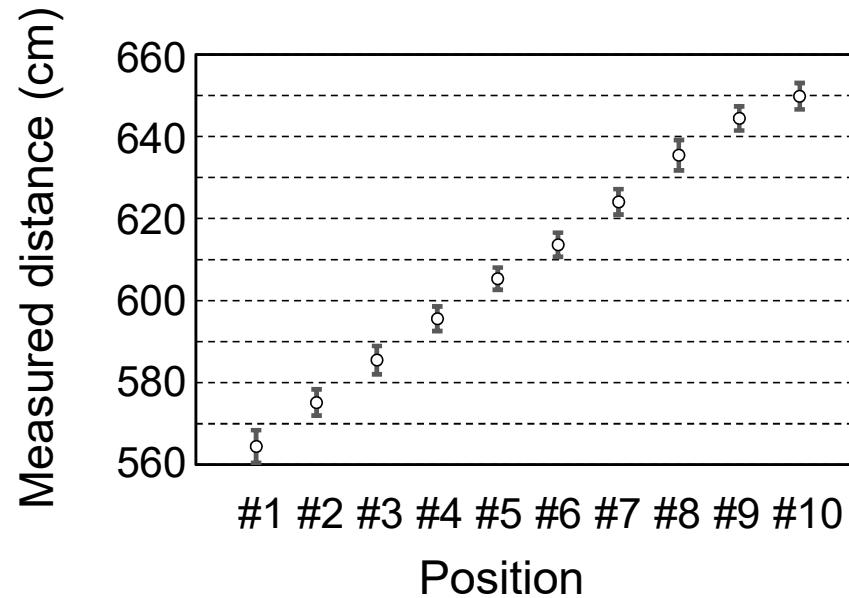
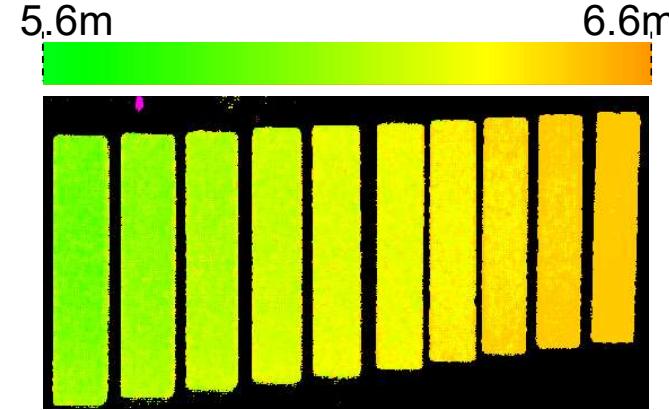
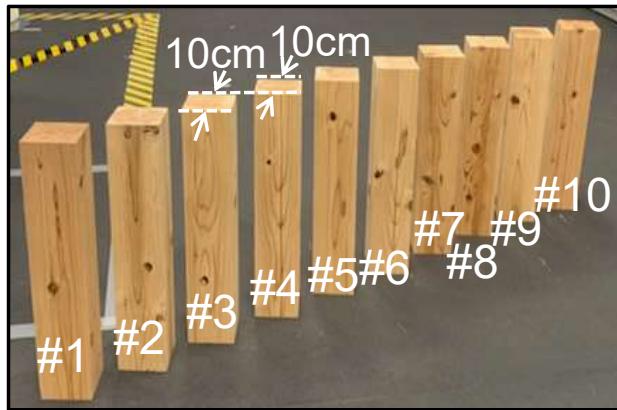
$$\Delta d = d \times \{(S_1 - S_2)/(S_1 + S_2)\} \times 1/2$$

Phase differentiation by multiple photon gating



$$\Delta d = d \times \{(S_1 - S_2)/(S_1 + S_2)\} \times 1/2$$

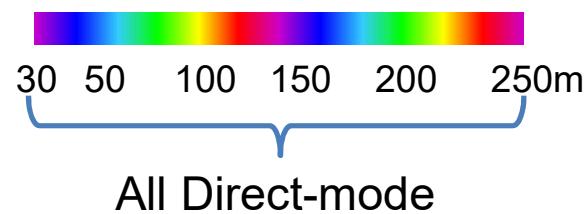
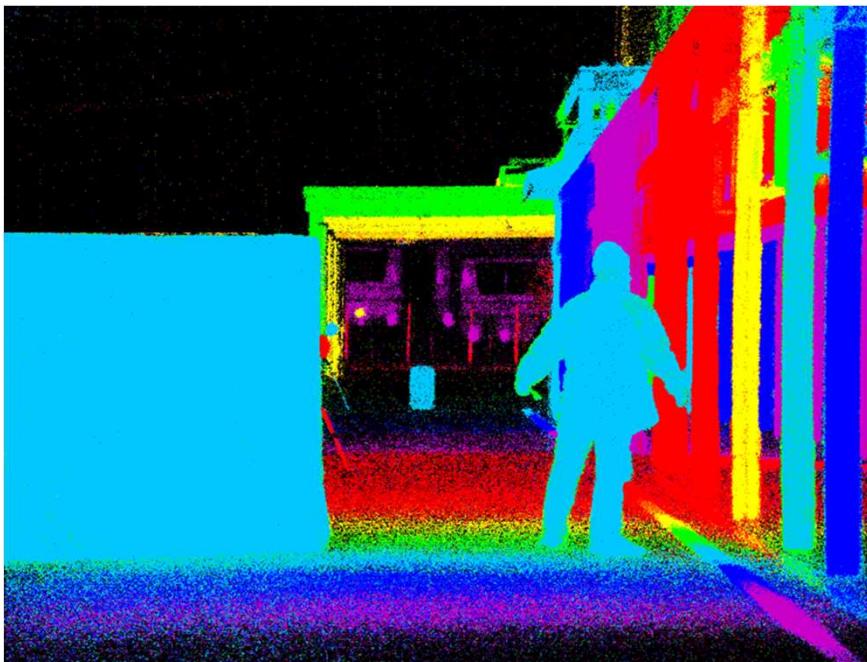
Verification of I-ToF operation and improved Δz



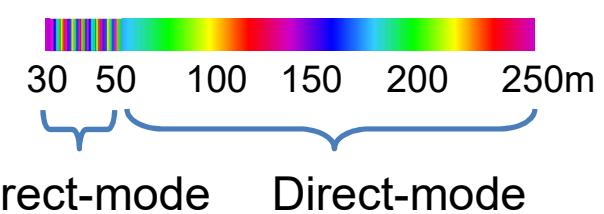
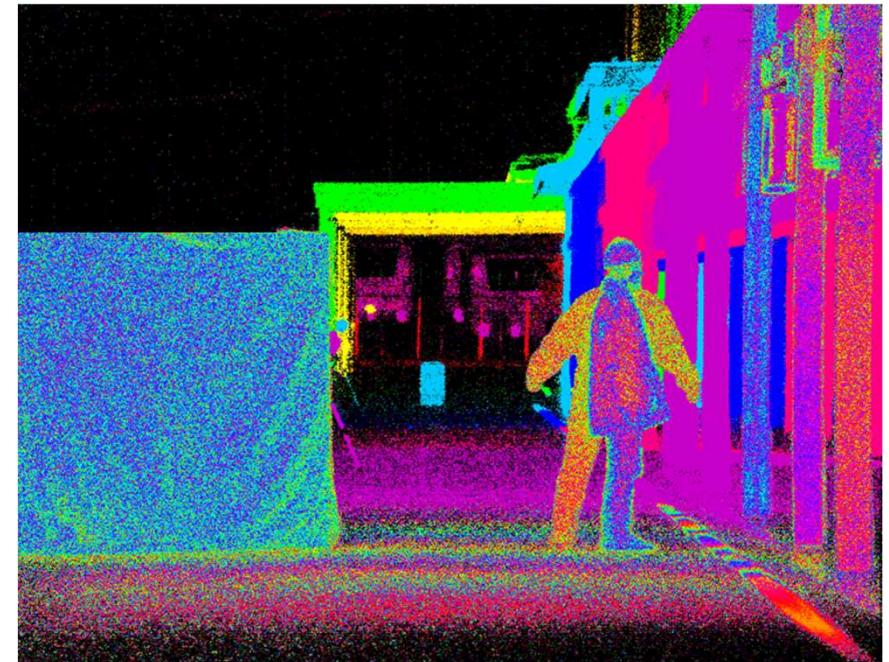
Std.Dev.:<7.4cm
Error:<1.4cm

Demonstration of mixed mode (long range)

Geiger-mode Direct-ToF image



Geiger-mode Direct-ToF-Indirect-ToF Mixed image



Summary

1. A 1.1 Mpixels vertical avalanche photodiode (VAPD) CMOS imager is demonstrated.
 - 10cm resolution@ Z~250 m
2. Charge control methods
 - Capacitive quenching
 - Charge packet spatula (CPS)
 - In-pixel photon count accumulator (ICA)
3. System Technologies
 - Photon-Counts-Equalizer (PCE)
 - Sub-range synthesis (SRS)+Phase difference detection
 - D-ToF/I-ToF mixed mode
 - ΔZ : 1.5m~7.5m (Long range~250 m)
 - ΔZ : 1cm~10cm (Short range~20m)

Thank you very much.